MURHB860CT

Power Rectifier

D²PAK Power Surface Mount Package

Designed for use in switching power supplies, inverters and as free wheeling diodes, these state−of−the−art devices have the following features:

Features

- Package Designed for Power Surface Mount Applications
- Ultrafast 35 Nanosecond Recovery Times
- 175°C Operating Junction Temperature
- Epoxy Meets UL 94 V−0 @ 0.125 in
- High Temperature Glass Passivated Junction
- High Voltage Capability to 600 V
- Low Leakage Specified @ 150°C Case Temperature
- Short Heat Sink Tab Manufactured — Not Sheared!
- Similar in Size to Industry Standard TO−220 Package
- Case: Epoxy, Molded
- Weight: 1.7 grams (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Pb−Free Packages are Available

MAXIMUM RATINGS (Per Leg)

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	600	V
Average Rectified Forward Current (Rated V_R, T_C = 120°C) Total Device	$I_{F(AV)}$	4.0 8.0	A
Peak Repetitive Forward Current (Rated V_R, Square Wave, 20 kHz, T_C = 120°C)	I_{FM}	8.0	A
Non−Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I_{FSM}	100	A
Operating Junction and Storage Temperature Range	T_J, T_{stg}	−65 to +175	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

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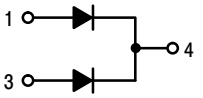
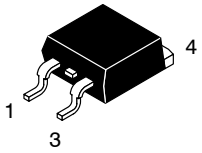
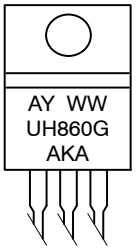
ULTRAFAST RECTIFIER
8.0 AMPERES, 600 VOLTS





D²PAK
CASE 418B
STYLE 3

MARKING DIAGRAM



A = Assembly Location
Y = Year
WW = Work Week
G = Pb−Free Package
AKA = Diode Polarity

ORDERING INFORMATION

Device	Package	Shipping†
MURHB860CT	D²PAK	50 Units/Rail
MURHB860CTG	D²PAK (Pb−Free)	50 Units/Rail
MURHB860CTT4	D²PAK	800/Tape & Reel
MURHB860CTT4G	D²PAK (Pb−Free)	800/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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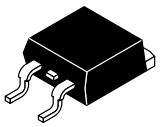
THERMAL CHARACTERISTICS (Per Leg)

Rating	Symbol	Value	Unit
Maximum Thermal Resistance, Junction−to−Case	$R_{\theta JC}$	3.0	°C/W
Maximum Thermal Resistance, Junction−to−Ambient	$R_{\theta JA}$	50	°C/W

ELECTRICAL CHARACTERISTICS (Per Leg)

Characteristic	Symbol	Max	Unit
Maximum Instantaneous Forward Voltage (Note 1) (i_F = 4.0 A, T_C = 150°C) (i_F = 4.0 A, T_C = 25°C)	v_F	2.5 2.8	V
Maximum Instantaneous Reverse Current (Note 1) (Rated DC Voltage, T_C = 150°C) (Rated DC Voltage, T_C = 25°C)	i_R	500 10	μA
Maximum Reverse Recovery Time (I_F = 1.0 A, di/dt = 50 A/μs)	t_{rr}	35	ns

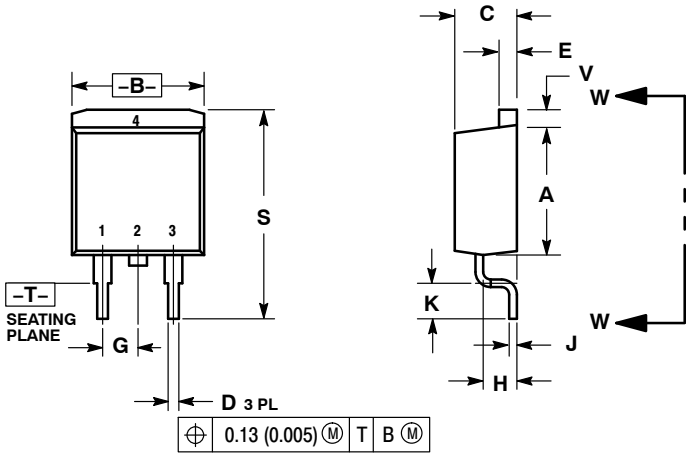
1. Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤2.0%



D²PAK 3
CASE 418B–04
ISSUE L

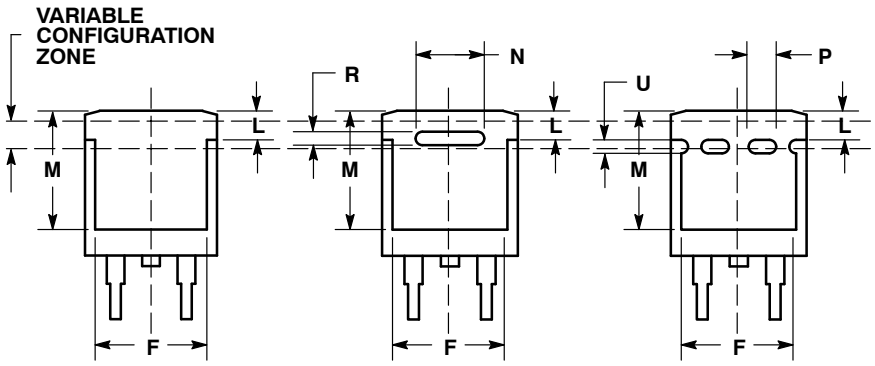
DATE 17 FEB 2015

SCALE 1:1



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. 418B–01 THRU 418B–03 OBSOLETE, NEW STANDARD 418B–04.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.340	0.380	8.64	9.65
B	0.380	0.405	9.65	10.29
C	0.160	0.190	4.06	4.83
D	0.020	0.035	0.51	0.89
E	0.045	0.055	1.14	1.40
F	0.310	0.350	7.87	8.89
G	0.100 BSC		2.54 BSC	
H	0.080	0.110	2.03	2.79
J	0.018	0.025	0.46	0.64
K	0.090	0.110	2.29	2.79
L	0.052	0.072	1.32	1.83
M	0.280	0.320	7.11	8.13
N	0.197 REF		5.00 REF	
P	0.079 REF		2.00 REF	
R	0.039 REF		0.99 REF	
S	0.575	0.625	14.60	15.88
V	0.045	0.055	1.14	1.40



VIEW W–W 1 | VIEW W–W 2 | VIEW W–W 3

STYLE 1:
PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

STYLE 2:
PIN 1. GATE
2. DRAIN
3. SOURCE
4. DRAIN

STYLE 3:
PIN 1. ANODE
2. CATHODE
3. ANODE
4. CATHODE

STYLE 4:
PIN 1. GATE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

STYLE 5:
PIN 1. CATHODE
2. ANODE
3. CATHODE
4. ANODE

STYLE 6:
PIN 1. NO CONNECT
2. CATHODE
3. ANODE
4. CATHODE

MARKING INFORMATION AND FOOTPRINT ON PAGE 2

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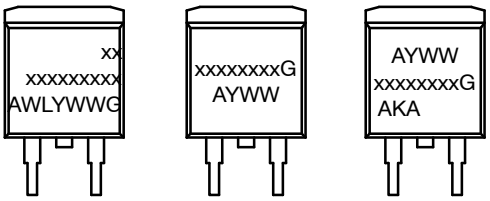
D²PAK 3
CASE 418B−04
ISSUE L

DATE 17 FEB 2015

GENERIC
MARKING DIAGRAM*

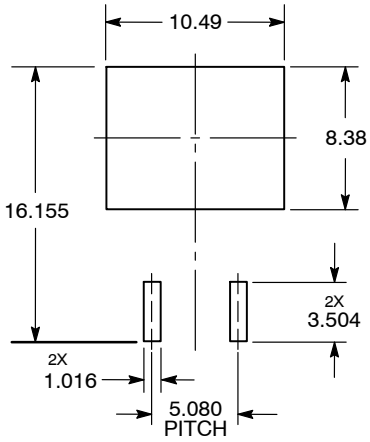


IC **Standard** **Rectifier**

xx	= Specific Device Code
A	= Assembly Location
WL	= Wafer Lot
Y	= Year
WW	= Work Week
G	= Pb−Free Package
AKA	= Polarity Indicator

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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